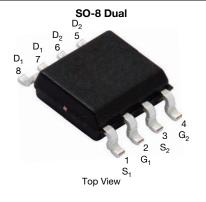


Dual N-Channel 60 V (D-S) 175 °C MOSFET

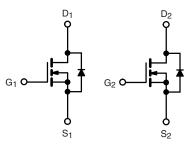
| PRODUCT SUMMARY | | | | |
|---|-------|--|--|--|
| V _{DS} (V) | 60 | | | |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$ | 0.028 | | | |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$ | 0.030 | | | |
| I _D (A) per leg | 7 | | | |
| Configuration | Dual | | | |



FEATURES

- TrenchFET[®] power MOSFET
- 100 % $\rm R_g$ and UIS tested





N-Channel MOSFET N-Ch

N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | |
|---|-------------------------|-----------------------------------|-------------|------|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | | V _{DS} | 60 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | V | |
| Continuous Drain Current | T _C = 25 °C | Ŀ | 7 | | |
| | T _C = 125 °C | l _D | 4 | | |
| Continuous Source Current (Diode Conduction) ^a | | I _S | 3.6 | А | |
| Pulsed Drain Current ^b | | I _{DM} | 28 | | |
| Single Pulse Avalanche Current | L = 0.1 mH | I _{AS} | 18 | | |
| Single Pulse Avalanche Energy | L = 0.1 mm | E _{AS} | 16.2 | mJ | |
| Maximum Power Dissipation ^b | T _C = 25 °C | Pn | 4 | W | |
| | T _C = 125 °C | гD | 1.3 | ٧٧ | |
| Operating Junction and Storage Temperature Range | e | T _J , T _{stg} | -55 to +175 | ۵°C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|----------------------------|------------------------|-------------------|-------|------|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | |
| Junction-to-Ambient | PCB Mount ^c | R _{thJA} | 110 | °C/W | |
| Junction-to-Foot (Drain) | | R _{thJF} | 34 | 0/10 | |

Notes

a. Package limited.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. When mounted on 1" square PCB (FR4 material).

| SPECIFICATIONS ($T_C = 25 \text{ °C}$, unless otherwise noted) | | | | | | | |
|---|---------------------|---|---|------|-------|-------|------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 V, I_D = 250 \mu A$ | | 60 | - | - | V |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | | 2.0 | 2.5 | V |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | - | - | ± 100 | nA |
| | | $V_{GS} = 0 V$ | V _{DS} = 60 V | - | - | 1 | μA |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{GS} = 0 V$ | $V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$ | - | - | 50 | |
| | | $V_{GS} = 0 V$ | $V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$ | - | - | 150 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{GS} = 10 \text{ V}$ | $V_{DS} \ge 5 V$ | 20 | - | - | А |
| | | $V_{GS} = 10 \text{ V}$ | I _D = 4.5 A- | | 0.028 | - | Ω |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 10 V$ | I _D = 4.5 A, T _J = 125 °C | - | 0.066 | - | |
| | 0.003(01) | V _{GS} = 10 V | I _D = 4.5 A, T _J = 175 °C | - | 0.081 | - | |
| | | $V_{GS} = 4.5 V$ | I _D = 4 A- | | 0.030 | - | |
| Forward Transconductance ^f | 9fs | V _{DS} | $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 4.5 \text{ A}$ | | 15 | - | S |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | | - | 600 | 750 | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 V \qquad \qquad V_{DS} = 25 V, f = 1 MHz$ | - | 110 | 140 | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | - | 50 | 62 | 1 |
| Total Gate Charge ^c | Qg | | | - | 11.7 | 18 | |
| Gate-Source Charge ^c | Q _{gs} | $V_{GS} = 10 V$ | $V_{DS} = 30 \text{ V}, \text{ I}_{D} = 5.3 \text{ A}$ | - | 1.8 | 2.7 | nC |
| Gate-Drain Charge ^c | Q _{gd} | | | - | 2.8 | 4.2 | |
| Gate Resistance | R _g | | f = 1 MHz | | - | 6 | Ω |
| Turn-On Delay Time ^c | t _{d(on)} | | | | 7 | 11 | |
| Rise Time ^c | t _r | $\label{eq:VDD} \begin{array}{l} V_{\text{DD}}=30 \text{ V}, \ R_{\text{L}}=6.8 \ \Omega \\ I_{\text{D}}\cong 4.4 \ \text{A}, \ V_{\text{GEN}}=10 \ \text{V}, \ R_{g}=1 \ \Omega \end{array}$ | | - | 3.3 | 5 | - ns |
| Turn-Off Delay Time ^c | t _{d(off)} | | | - | 22.4 | 33.5 | |
| Fall Time ^c | t _f | | | - | 2.1 | 3.2 | |
| Source-Drain Diode Ratings and Characteristics ^b | | | | | | | |
| Pulsed Current ^a | I _{SM} | | | - | - | 28 | А |
| Forward Voltage | V _{SD} | I _F = 2 A, V _{GS} = 0 V | | - | 0.75 | 1.1 | V |
| | | | | | | | 4 |

Notes

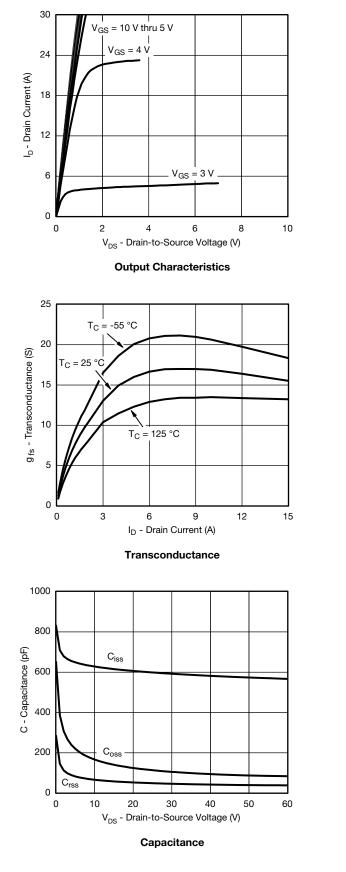
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

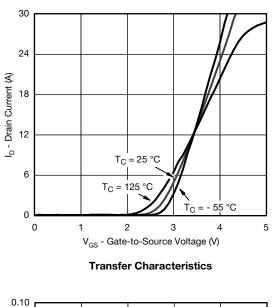
c. Independent of operating temperature.

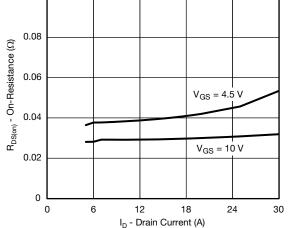
Bsemi Bsemi.com

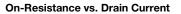


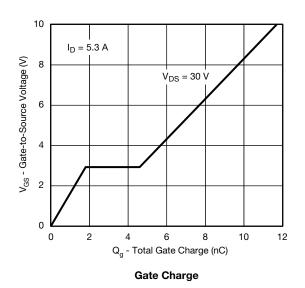
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)





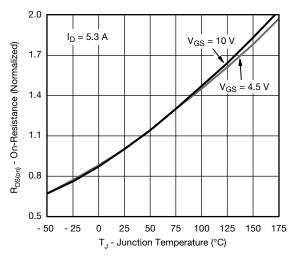




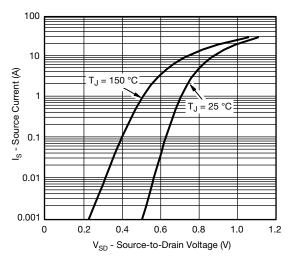




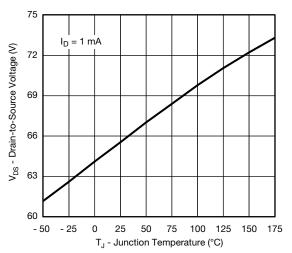
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



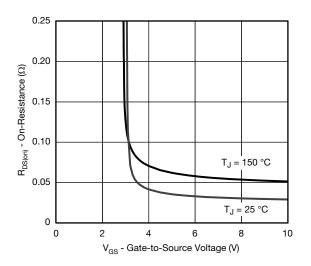
On-Resistance vs. Junction Temperature



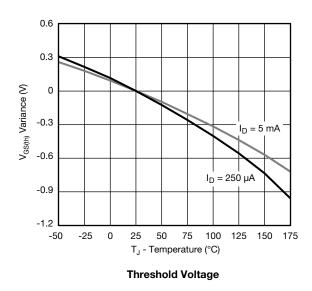
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

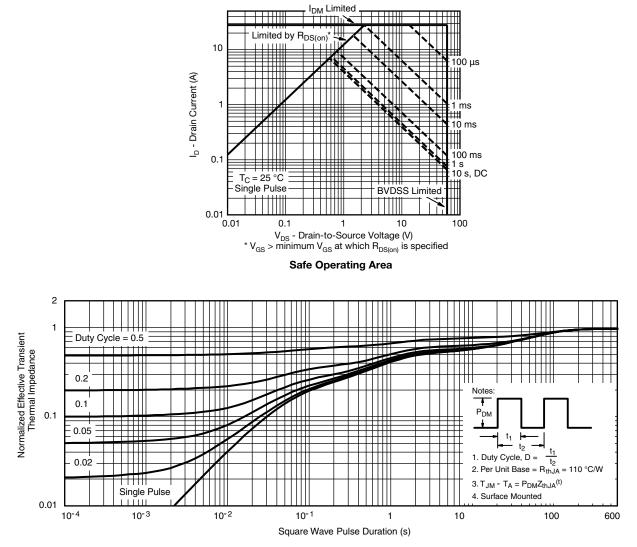


On-Resistance vs. Gate-to-Source Voltage





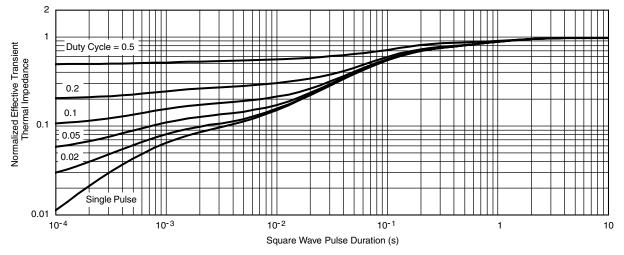
THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



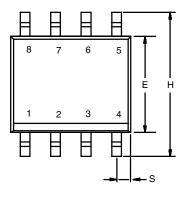
THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

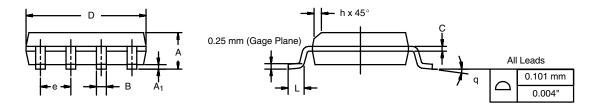


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012



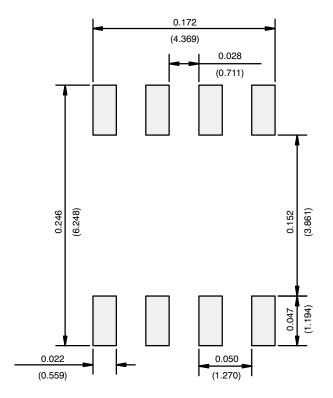


| | MILLIM | IETERS | INCHES | | |
|---|--------|--------|-----------|-------|--|
| DIM | Min | Мах | Min | Max | |
| A | 1.35 | 1.75 | 0.053 | 0.069 | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | |
| E | 3.80 | 4.00 | 0.150 | 0.157 | |
| е | 1.27 | BSC | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | |
| q | 0° | 8° | 0° | 8° | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | |
| ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498 | | | | | |

SI9945AEY-T1-E3



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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